

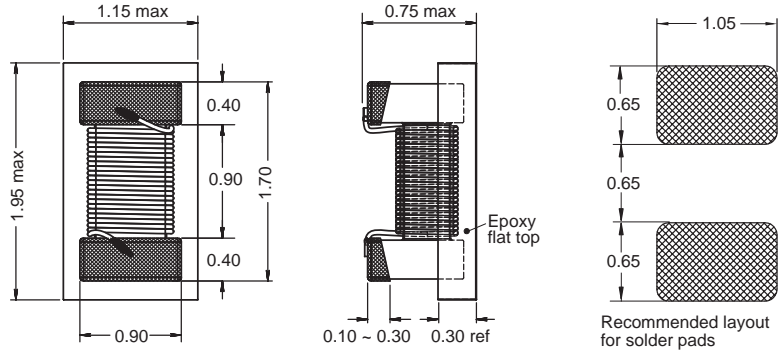
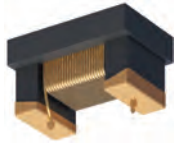
# 0603 FLP



Semi-shielded

Low Profile Design

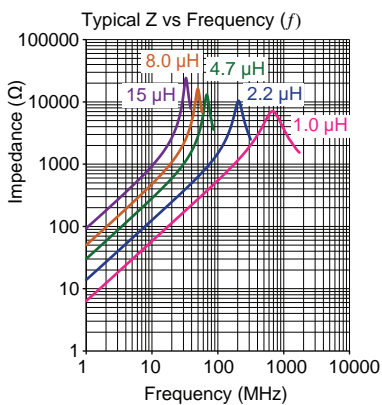
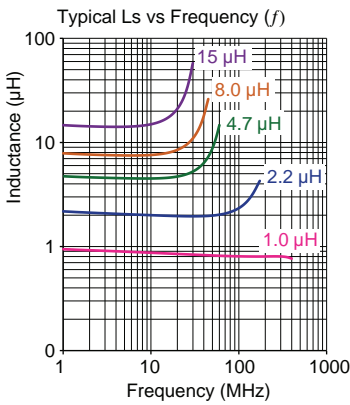
Engineer's Kit: EK-0603FLP-X



Recommended layout for solder pads

(Wire wound - open)

Chip Inductors for RF Applications



Part No	Inductance	f <sub>L</sub>	Tol	SRF	DCR	Rated DC Current (A)	
	L (μH)	(MHz)	± (%)	typ (MHz)	max (Ω)	I <sub>sat</sub>	I <sub>rms</sub>
0603FLP-R56M-YY	0.56	1.0	20	850	0.300	0.700	0.680
0603FLP-R68M-YY	0.68	1.0	20	670	0.350	0.620	0.600
0603FLP-1R0M-YY	1.0	1.0	20	450	0.380	0.560	0.540
0603FLP-1R5M-YY	1.5	1.0	20	175	0.520	0.440	0.420
0603FLP-2R2M-YY	2.2	1.0	20	150	0.750	0.380	0.350
0603FLP-4R7M-YY	4.7	1.0	20	55	1.050	0.300	0.300
0603FLP-6R8M-YY	6.8	1.0	20	40	1.500	0.240	0.280
0603FLP-8R0M-YY	8.0	1.0	20	40	2.500	0.200	0.200
0603FLP-100M-YY	10	1.0	20	30	2.900	0.180	0.180
0603FLP-150M-YY	15	1.0	20	25	3.600	0.140	0.140

Core Material: Ferrite

Revision date: 08 Mar 2024

SPQ: Taped / Reel 1000 [-08]  
4000 [-01]  
15000 [-04]

Remarks: Unlisted inductance values available upon request.